uClamp0555T Ultra Small µClamp® 5-Line ESD Protection

PROTECTION PRODUCTS - MicroClamp®

Description

μClamp® TVS diodes are designed to protect sensitive electronics from damage or latch-up due to ESD. They are designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and other portable electronics. They feature large cross-sectional area junctions for conducting high transient currents. This device offers desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

The $\mu\text{Clamp}^{\$}0555T$ is in a 6-pin SLP1007N6T package. It measures 1.0 x 0.7 mm with a nominal height of only 0.4mm. The leads are finished with lead-free NiPdAu. Each device will protect five lines operating at 5 volts. It gives the designer the flexibility to replace multiple single line devices in space constrained applications. They may be used to meet the ESD immunity requirements of IEC 61000-4-2. The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Features

- ◆ High ESD withstand Voltage: +/-17kV (Contact) per IEC 61000-4-2
- ◆ Very small PCB area: 0.7mm²
- Protects up to five data lines
- Low reverse current: <10nA typical (VR=5V)</p>
- ◆ Working voltage: +/- 5V
- ◆ Low capacitance: <9pF (VR=0V)
- Low dynamic resistance: 0.55 Ohms (Typ)
- Solid-state silicon-avalanche technology

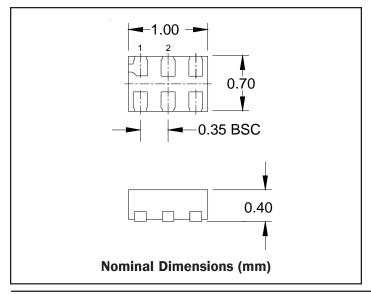
Mechanical Characteristics

- ◆ SLP1007N6T package
- ◆ Pb-Free, Halogen Free, RoHS/WEEE Compliant
- ♦ Nominal Dimensions: 1.0 x 0.7 x 0.40 mm
- ◆ Lead Pitch: 0.35mm
- Lead Finish: NiPdAu
- Molding compound flammability rating: UL 94V-0
- ◆ Marking : Marking code + dot matrix date code
- Packaging : Tape and Reel

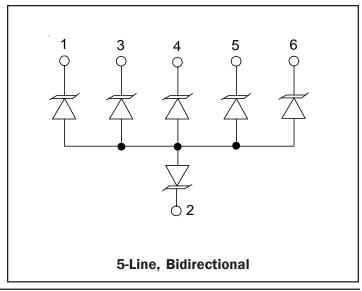
Applications

- Cellular Handsets & Accessories
- Keypads, Side Keys, Audio Ports
- LCD Connectors
- Digital Lines
- Analog Video

Dimensions



Schematic & PIN Configuration





Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20μs)	P _{pk}	30	Watts
Maximum Peak Pulse Current (tp = 8/20μs)	I _{pp}	2	Amps
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	+/- 19 +/- 17	kV
Operating Temperature	T _J	-55 to +125	°C
Storage Temperature	T _{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C)

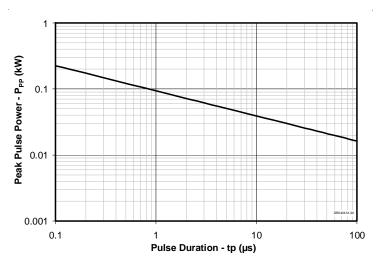
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}	Any I/O Pin to GND			5	V
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA Any I/O Pin to GND	6	8.2	9.5	V
Reverse Leakage Current	I _R	V _{RWM} = 5V, T=25°C Any I/O Pin to GND		3	50	nA
Clamping Voltage	V _c	I _{PP} = 2A, tp = 8/20µs Any I/O Pin to GND			15	V
ESD Clamping Voltage	V _c	I _{pp} = 16A, tlp = 0.2/100ns		17		V
Dynamic Resistance	R _{Dyn}	tp = 100ns		0.55		Ohms
Junction Capacitance	C _j	V _R = OV, f = 1MHz Any I/O Pin to GND		7	9	pF

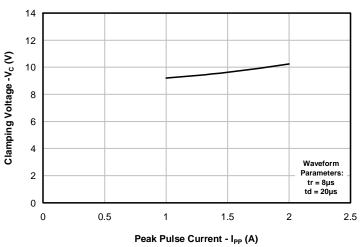


Typical Characteristics

Non-Repetitive Peak Pulse Power vs. Pulse Time

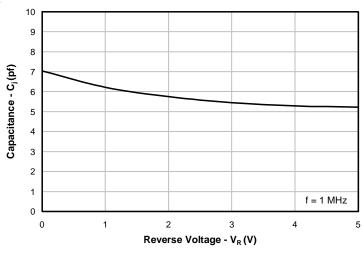
Clamping Voltage vs. Peak Pulse Current (tp=8/20us)

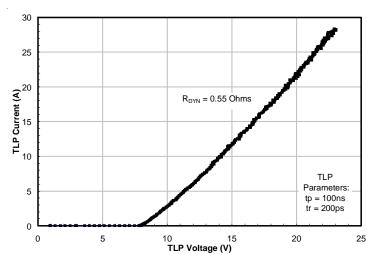




Junction Capacitance vs. Reverse Voltage

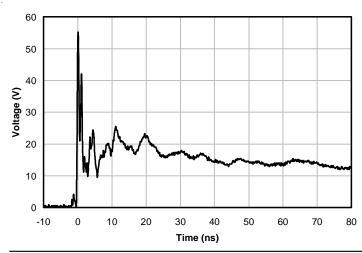
TLP Characteristic

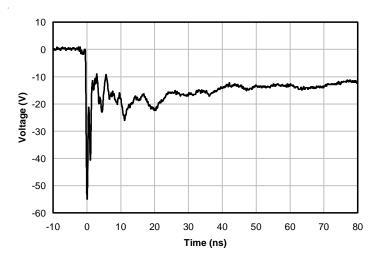




ESD Clamping (+8kV Contact per IEC 61000-4-2)

ESD Clamping (-8kV Contact per IEC 61000-4-2)

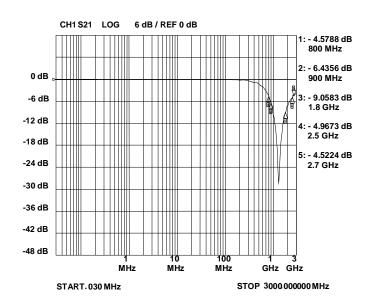




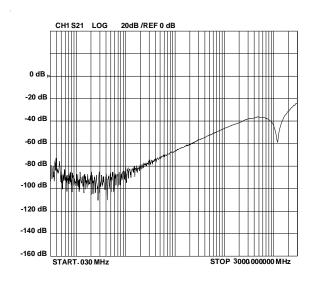


Typical Characteristics

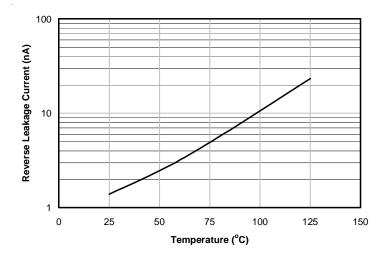
Typical Insertion Loss S21



Analog Crosstalk



Reverse Leakage Current (IR) vs. Temperature





Applications Information

Device Connection Options

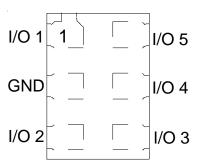
The μ Clamp0555T is designed to protect five data lines operating up to 5 volts. The device is bidirectional and may be used on lines where the signal polarity is above and below ground. The diagram at the right shows an example pin configuration with pin 2 connected to ground. However, due to the device symmetry, any pin may be connected to ground with the remaining pins connected to the protected lines.

Assembly Guidelines

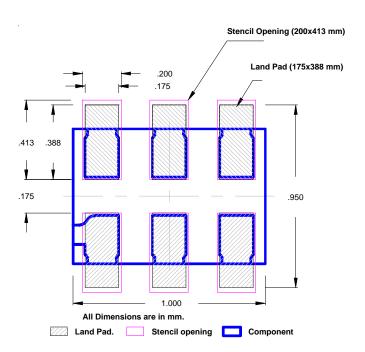
The small size of this device means that some care must be taken during the mounting process to insure reliable solder joint. The table below provides Semtech's recommended assembly guidelines for mounting this device. The figure at the right details Semtech's recommended aperture based on the below recommendations. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. The exact manufacturing parameters will require some experimentation to get the desired solder application.

Assembly Parameter	embly Parameter Recommendation	
Solder Stencil Design	Laser cut, Electro-polished	
Aperture shape	Rectangular	
Solder Stencil Thickness	0.100 mm (0.004")	
Solder Paste Type	Type 4 size sphere or smaller	
Solder Reflow Profile	Per JEDEC J-STD-020	
PCB Solder Pad Design	Non-Solder mask defined	
PCB Pad Finish	OSP OR NiAu	

Example Pin Configuration

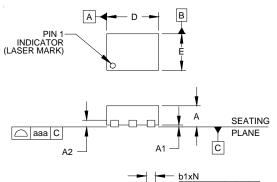


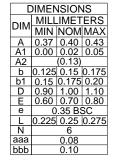
Recommended Mounting Pattern

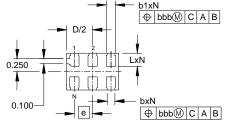




Outline Drawing - SLP1007N6T



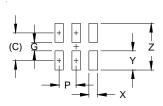




NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

Land Pattern - SLP1007N6T



DIMENSIONS				
DIM	IM MILLIMETERS			
С	(0.563)			
G	0.175			
Р	0.35			
Χ	0.175			
Υ	0.388			
Z	0.95			

NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
 CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
 COMPANY'S MANUFACTURING GUIDELINES ARE MET.



Marking Code



Notes:

Marking will also include line matrix date code

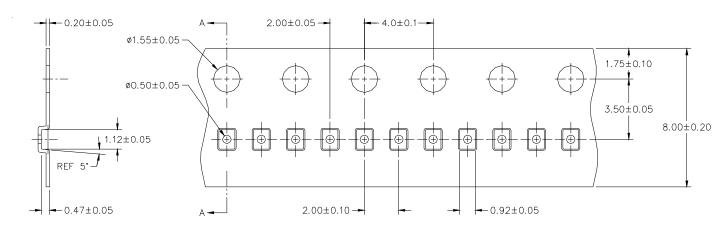
Ordering Information

Part Number	Qty per Reel	Reel Size	
uClamp0555T.TNT	10,000	7 Inch	

Notes:

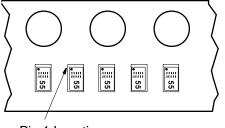
MicroClamp, uClamp and μ Clamp are trademarks of Semtech Corporation

Carrier Tape Specification



SECTION A-A

Device Orientation in Tape



Pin 1 Location (Towards Sprocket Holes)

Contact Information

Semtech Corporation Protection Products Division 200 Flynn Rd., Camarillo, CA 93012 Phone: (805)498-2111 FAX (805)498-3804